

PART ONE: General description

Spin-On Glass

Process name

Process Code

10/16/00

Last Update

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Author

Contact Information (Email)

Etching spin-on glass.
Spin-on glass can be used as a passivation layer for metal.

General description of process

PART TWO: Details

RIE Etching

Pressure Set

150

Oxygen Set

25

RF Power Set

100

CHF3 Set

54

End Point Set

100

SF6 Set

0

Process Time

3

min

Base Pressure Set

150

PART THREE: General Comments

Etch rate – Approx. 110 (nm/min)
Etch Rate in BOE 45 (nm/min) – not recommended (huge under-cut)
PhotoResist leftovers are hard to remove – can use Oxygen plasma after acetone cleaning.